

I Claim,

1. A light emitting diode includes a heat conduction substrate, a circuitry on the heat conduction substrate, an insulation layer between the heat conduction substrate and the circuitry, multiple light emitting chips distributed among the circuitry and in the space above the heat conduction substrate and connected to the circuitry through a metal conductor, and a light permeable protection layer covering up the light emitting chips.
2. A light emitting diode as claimed in Claim 1, wherein, a recess or a trough is formed on the heat conduction substrate, multiple light emitting chips are distributed at the bottom of the recess or the trough; and a light permeable protection layer covers up those light emitting chips and the recess or the trough.
3. A light emitting diode as claimed in Claim 2, wherein, a recess or a trough is formed on the heat conduction substrate, multiple light emitting chips are distributed at the bottom of the recess or the trough covered up with a light permeable protection layer.
4. A light emitting diode as claimed in Claim 1, wherein, those light emitting chips are distributed among the circuitry and in the space above the insulation layer.
5. A light emitting diode as claimed in Claim 2, wherein, those light emitting chips are glued among the circuitry and in the space above the heat conduction substrate or the insulation layer.
6. A light emitting diode as claimed in Claim 1, wherein, a light permeable optical lens is provided on the light-emitting chip fixed above the light emitting chip.
7. A light emitting diode as claimed in Claim 1, wherein, a circuit is formed first among multiple light emitting chips and both ends of the circuit are then connected to the circuitry on the substrate.
8. A light emitting diode as claimed in Claim 1, wherein, the LED is made into a module, multiple modules are distributed on a support board, a circuit or a conductor is used for connection among those multiple modules locked to the

support board.

9. A light emitting diode as claimed in Claim 1, wherein, the heat conduction substrate is made in a bow shape with those light emitting chips and the circuitry distributed thereon.

- 5 10. A light emitting diode as claimed in Claim 1, wherein, a fan is adapted to the heat conduction substrate.

11. A light emitting diode as claimed in Claim 2, wherein, one or more than one recess or trough is provided among the circuitry and above the heat conduction substrate and multiple light emitting chips at the bottom of the recess or trough are
10 connected to one another with a circuit.

12. A light emitting diode as claimed in Claim 1, wherein, The heat conduction substrate 1 is intergraded with a power dissipation member.

13. A light emitting diode as claimed in Claim 12, wherein, the power dissipation member is made into a stick, a sheet or in any other form that facilitates power
15 dissipation.